

PRINTER RUSH
(PTO ASSISTANCE)

Application : 10/776,084 Examiner : Trung Dang GAU : 2823

From : S. Winslow Location : IDC FMF FDC Date : 2-1-06

Tracking #: EPM 10/776,084 Week Date: 1-16-06

DOC CODE	DOC DATE	MISCELLANEOUS
<input type="checkbox"/> 1449		<input type="checkbox"/> Continuing Data
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<input type="checkbox"/> IIFW		<input type="checkbox"/> Fees
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<input type="checkbox"/> OATH		
<input type="checkbox"/> 312		
<input checked="" type="checkbox"/> SPEC	<u>2-11-04</u>	

[RUSH] MESSAGE: Page 2 of specification, paragraph 006,
describes Figure 2 instead of Figure 3.

Please advise

Thanks

[XRUSH] RESPONSE: Type, corrected

INITIALS: def

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REV 10/04

BRIEF DESCRIPTION OF THE DRAWINGS

[0004] FIGURE 1 is a sectional view of an example of micro device die fabricated according to one exemplary embodiment of a packaging and singulation method of the present invention.

[0005] FIGURE 2 is a sectional view of the formation of seals on a multi-lid substrate according to an exemplary embodiment.

[0006] FIGURE 2 is a sectional view illustrating the formation of a trench pattern in the multi-lid substrate to form a protective multi-device lid according to an exemplary embodiment.

[0007] FIGURE 4 is a top plan view of the protective multi-device lid of FIGURE 3 according to an exemplary embodiment.

[0008] FIGURE 4A is a top plan view of another exemplary embodiment of the protective multi-device lid of FIGURE 4.

[0009] FIGURE 5 is a sectional view illustrating the protective multi-device lid of FIGURE 4 coupled to a micro device wafer according to an exemplary embodiment.

[0010] FIGURE 6 is a sectional view illustrating the formation of access channels through the protective multi-device lid of FIGURE 5 prior to singulation of the micro device wafer of FIGURE 5 into individual dies according to an exemplary embodiment.

[0011] FIGURE 7 is a top plan view of the joined protective multi-device lid and micro device wafer of FIGURE 6 after the formation of the access channels according to an exemplary embodiment.

DETAILED DESCRIPTION OF AN EXAMPLE EMBODIMENT

[0012] FIGURE 1 is a sectional view of a completed micro device die 20 fabricated according to one embodiment of the present invention. Micro device die 20 includes device substrate 22, micro device 24 and protective single device lid 26. Substrate 22 serves as a base or foundation for micro device 24. In the particular embodiment illustrated, substrate 22 generally comprises a layer of silicon. In alternative